

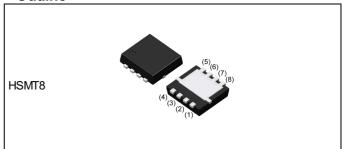
RQ3P300BH

Nch 100V 39A Power MOSFET

V _{DSS}	100V
R _{DS(on)} (Max.)	15.5mΩ
I _D	±39A
P _D	32W

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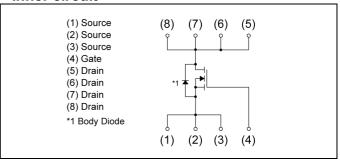
Outline



Features

- 1) Low on resistance
- 2) Small Surface Mount Package
- 3) Pb-free plating; RoHS complian

•Inner circuit



Packaging specifications

	Jing opcomoducino	
	Packing	Embossed Tape
	Reel size (mm)	330
Type	Tape width (mm)	12
	Quantity (pcs)	3000
	Taping code	TB1
	Marking	P300BH

Application

Primary side switch

Moter drives

DC/DC converter

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	100	V	
Continuous drain current	\/ = 10\/	I _D *1	±39	Α
Continuous drain current	V _{GS} = 10V	I _D	±10	Α
Pulsed drain current	I _{DP} *2	±40	Α	
Gate - Source voltage	V_{GSS}	±20	V	
Avalanche current, single pulse	I _{AS} *3	10	Α	
Avalanche energy, single pulse	E _{AS} *3	40	mJ	
Dawar dissination		P _D *1	32	W
Power dissipation		P _D *4	2.0	W
Junction temperature	T _j	150	°C	
Operating junction and storage te	T _{stg}	-55 to +150	°C	

●Thermal resistance

Doromotor	Cymhol	Values			l limit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	-	3.9	°C/W
Thermal resistance, junction - ambient	R _{thJA} *4	-	-	62.5	°C/W

● Electrical characteristics (T_a = 25°C)

Davamatav	Cymah al	Conditions		Values		Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Uriit	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j} I_D = 1 \text{mA}$ referenced to 25°C		62.3	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V	-	-	10	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	1	1	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 1mA$	2.0	-	4.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-4.5	-	mV/°C	
Static drain - source	D *5	V _{GS} = 10V, I _D = 10A	-	11.9	15.5	m0	
on - state resistance	R _{DS(on)} *5	V _{GS} = 6V, I _D = 10A	-	15.6	24.0	mΩ	
Gate resistance	R_{G}	-	0.9	1.7	3.4	Ω	
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = 5V, I _D = 10A	8.8	-	-	S	

^{*1}T_c =25°C, Limited only by maximum temperature allowed.



^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \simeq 0.5mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Mounted on a Cu board (40×40×0.8mm)

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C)

Daramatar	Cymahal	Conditions		Unit			
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Urill	
Input capacitance	C _{iss}	V _{GS} = 0V	*510	1020	*2040		
Output capacitance	C _{oss}	V _{DS} = 50V	*115	230	*460	pF	
Reverse transfer capacitance	C_{rss}	f = 1MHz	*8.5	17	*34		
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \simeq 50V, V_{GS} = 10V$	1	18	-		
Rise time	t r*5	I _D = 5A	1	20	-	no	
Turn - off delay time	$t_{d(off)}^{*5}$	$R_L \simeq 10\Omega$	1	34	-	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	14	-		

^{*:} Guarantee of Design

● Gate charge characteristics (T_a = 25°C)

Daramatar	Cymahal	Conditions	Values			Lloit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	V _{DD} ≃ 50V,	*9.0	18.0	*36.0	
Gate - Source charge	Q _{gs} *5	I _D = 10A,	*2.2	4.4	*8.8	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	*2.6	5.2	*10.4	

^{*:} Guarantee of Design

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Darameter	Cumb of	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I _S	T = 25°C	-	-	1.67	Α
Pulse forward current	l _{SP} *2	T _a = 25℃	-	-	40	Α
Forward voltage	V_{SD}^{*5}	$V_{GS} = 0V, I_{S} = 1.67A$	-	-	1.2	V
Reverse recovery time	t _{rr} *5	I _S = 10A, V _{GS} =0V	-	48	-	ns
Reverse recovery charge	Q_{rr}^{*5}	di/dt = 100A/µs	-	31	-	nC

 $^{^*1}T_c$ =25°C, Limited only by maximum temperature allowed.

^{*2} Pw \leq 10µs, Duty cycle \leq 1%

^{*3} L \simeq 0.5mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Mounted on a Cu board (40×40×0.8mm)

^{*5} Pulsed

Fig.1 Power Dissipation Derating Curve

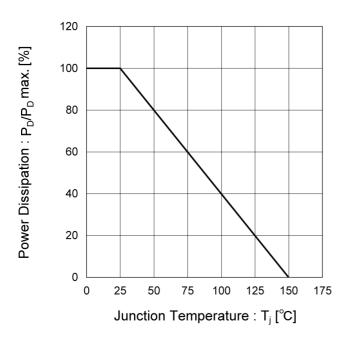
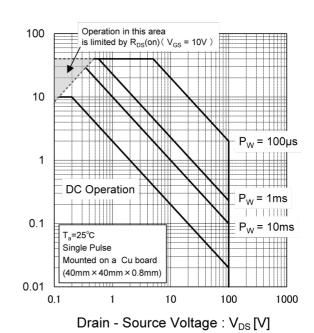


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

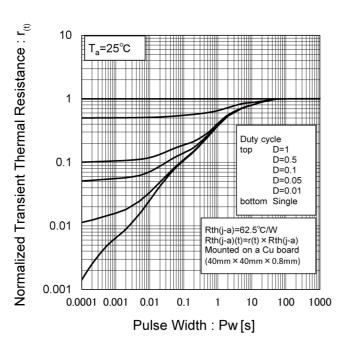


Fig.4 Single Pulse Maximum Power Dissipation

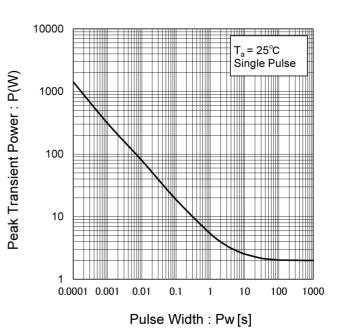
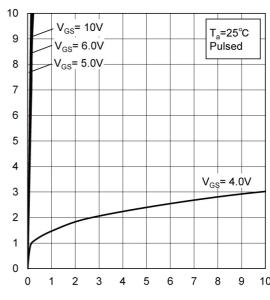


Fig.5 Typical Output Characteristics(I)

10 T_a=25°C V_{GS}= 10V 9 Pulsed $V_{GS} = 6.0V$ 8 V_{GS}= 5.0V Drain Current : I_D [A] 7 6 5 4 3 2 V_{GS}= 4.0V 0 0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 0 Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

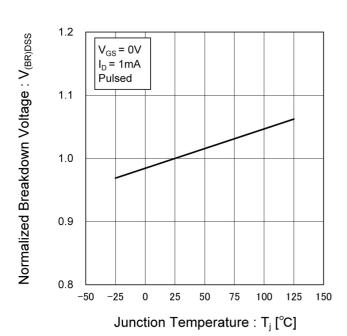


Fig.8 Typical Transfer Characteristics

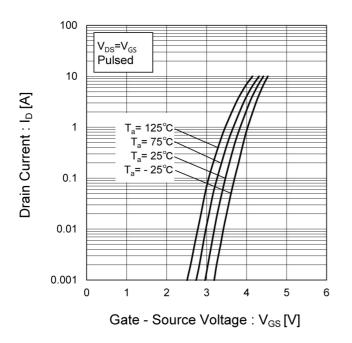
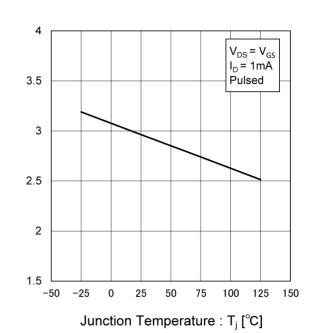


Fig.9 Gate Threshold Voltage vs.
Junction Temperature



Gate Threshold Voltage: VGS(th) [V]

Fig.10 Forward Transfer Admittance vs.
Drain Current

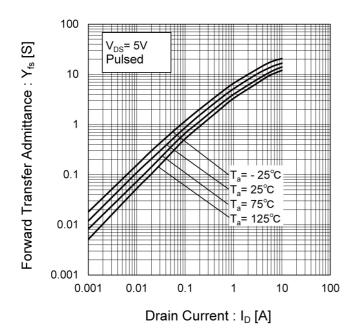


Fig.11 Drain Current Derating Curve

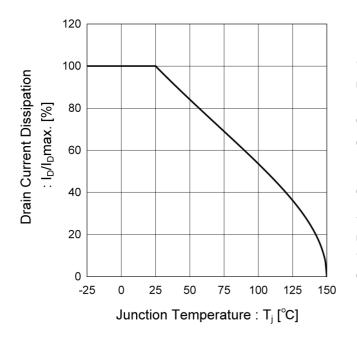


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

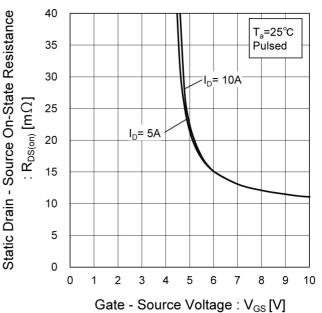


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

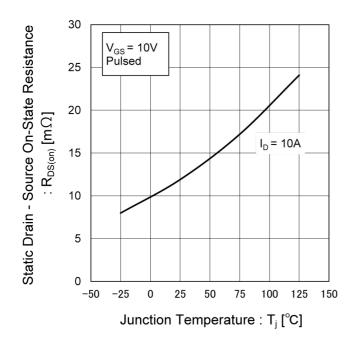


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

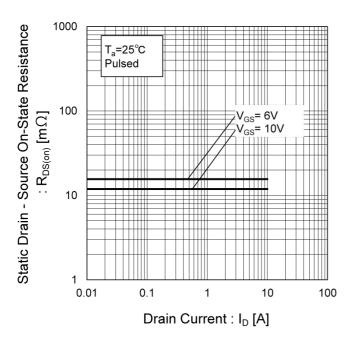


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

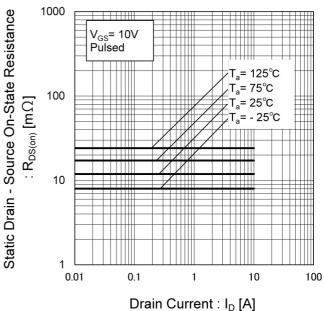


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

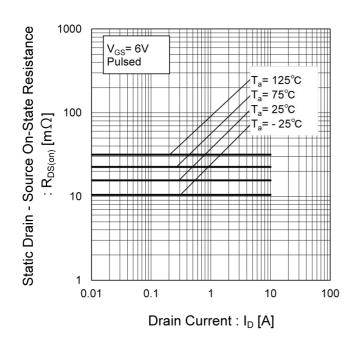


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

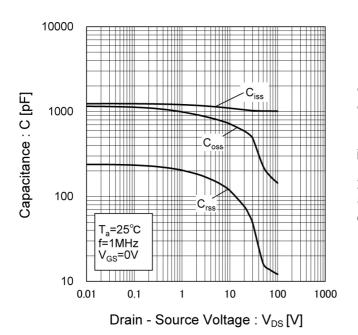


Fig.18 Switching Characteristics

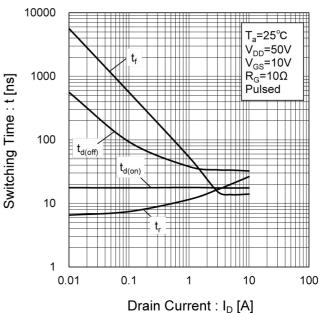


Fig.19 Typical Gate Charge

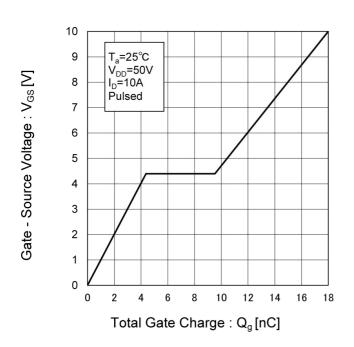
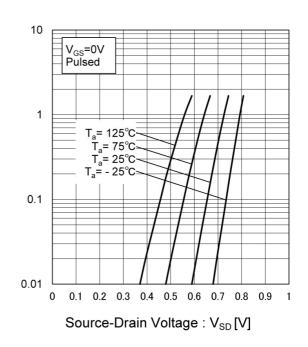


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

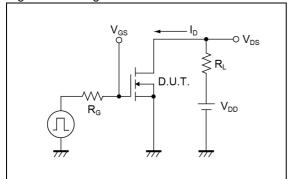


Fig.1-2 Switching Waveforms

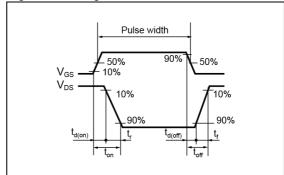


Fig.2-1 Gate Charge Measurement Circuit

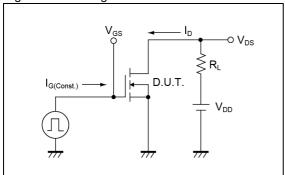


Fig.2-2 Gate Charge Waveform

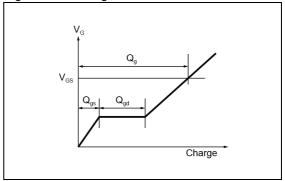


Fig.3-1 Avalanche Measurement Circuit

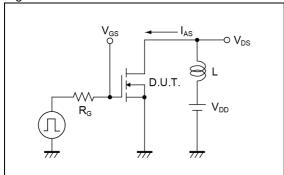
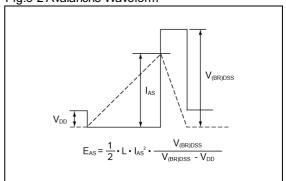


Fig.3-2 Avalanche Waveform



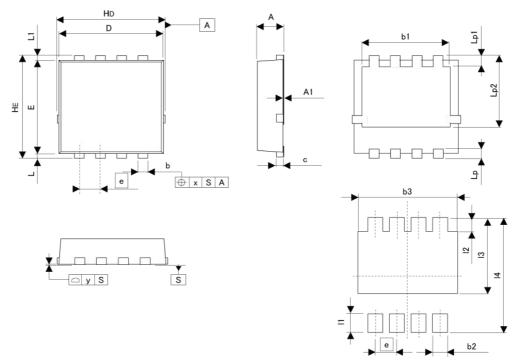
Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions

HSMT8 (TB1)

(3.3x3.3)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INCI	HES
DIIVI	MIN	MAX	MIN	MAX
Α	0.65	0.85	0.026	0.033
A1	0.00	0.10	0.000	0.004
b	0.24	0.42	0.009	0.017
b1	2.29	2.69	0.090	0.106
С	0.05	0.25	0.002	0.010
D	3.05	3.25	0.120	0.128
Е	2.95	3.15	0.116	0.124
е	0.	65	0.026	
HD	3.20	3.40	0.126	0.134
HE	3.20	3.40	0.126	0.134
L	0.05	0.23	0.002	0.009
L1	0.05	0.23	0.002	0.009
Lp	0.20	0.60	0.008	0.024
Lp1	0.20	0.60	0.008	0.024
Lp2	1.83	2.63	0.072	0.104
Х	1-1	0.10	-	0.004
у	-	0.10	-	0.004

DIM	DIM MILIME		INC	HES
DIIVI	MIN	MAX	MIN	MAX
b2	-	0.52	(1-)	0.020
b3	-	2.79	-	0.110
11	-	0.70	2-2	0.028
12	(-)	0.70	(-)	0.028
13	12	2.53	2	0.100
14	-	3.60	(-)	0.142

Dimension in mm/inches



Notice

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JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГУООШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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